



BSI Standards Publication

Mechanical standardization of semiconductor devices

Part 6-19: Measurement methods of the
package warpage at elevated temperature
and the maximum permissible warpage

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National foreword

This British Standard is the UK implementation of EN 60191-6-19:2010. It is identical to IEC 60191-6-19:2010.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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